substrate W. The probe card 12 is connected to the tester 4 via an interface 13. At the time of inspection of electrical characteristics, each probe 12a contacts the electrode part E of each electronic device D of the substrate W, supplies power from the tester 4 to the electronic device D via the interface 13, and also transfers a signal from the electronic device D to the tester 4 via the interface 13.

[0015]

A Front Opening Unified Pod (FOUP), which is a transfer container accommodating a substrate W, is arranged in the loader 3. The loader 3 also has a transfer mechanism (not shown) for transferring the substrate W. The transfer mechanism takes out the substrate W accommodated in the FOUP and transfers the substrate W to the stage 10 of the accommodation chamber 2. The transfer mechanism also receives the substrate W, for which the inspection of the electrical characteristics of the electronic device D has been completed, from the stage 10 and accommodates the substrate W in the FOUP.

[0016]

The tester 4 has a test board (not shown) that reproduces a part of the circuit configuration of a motherboard on which the electronic device D is mounted. The test board of the tester 4 is also connected to a tester computer 15 that determines whether the electronic device D is acceptable, based on a signal from the electronic device D. In the tester 4, the circuit configurations of a plurality of types of motherboards can be reproduced by replacing the test board. In addition, a plurality of probes 12a of the probe card 12 are provided, and are respectively brought into contact with a plurality of electrode parts E of the electronic device D. The tester 4 also has a plurality of detection means for detecting electrical characteristics of the electronic device D. Thereby, the tester 4 detects a plurality of electrical characteristics of the electronic device D.